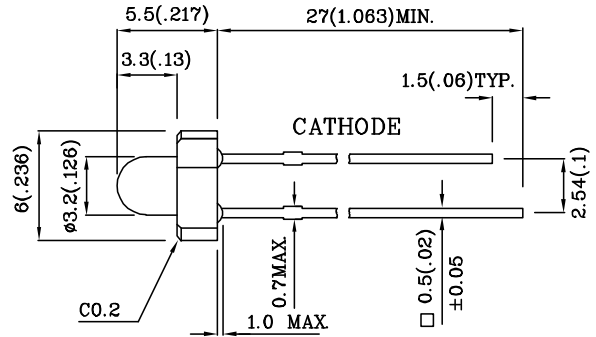
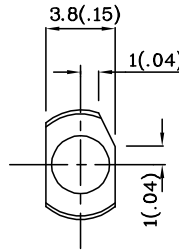


**Features**

- LOW POWER CONSUMPTION.
- WIDE VIEWING ANGLE.
- AVAILABLE ON TAPE FOR AUTOMATIC MOUNTING MACHINE.
- LONG LIFE-SOLID STATE RELIABILITY.
- RoHS COMPLIANT.



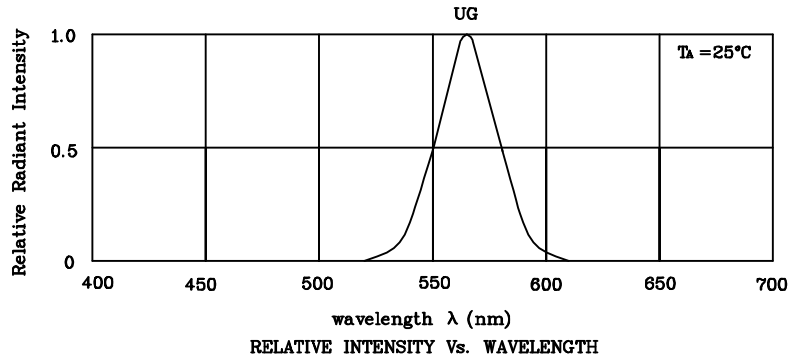
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25(0.01)$ " unless otherwise noted.

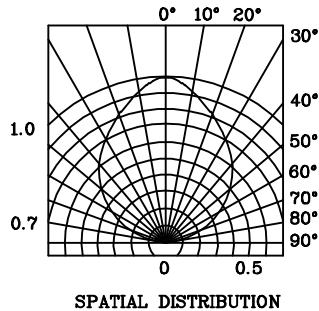
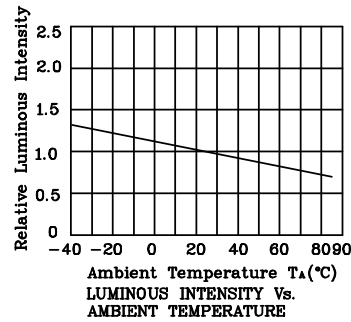
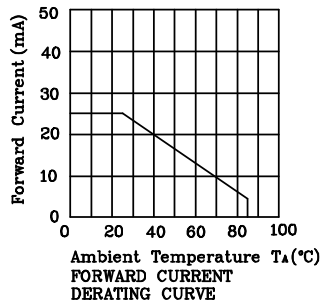
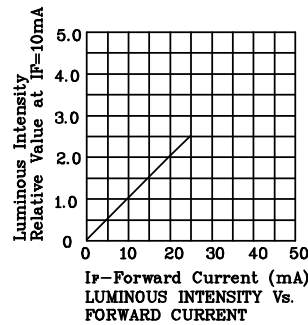
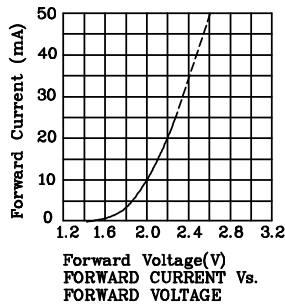
Absolute maximum ratings (TA=25°C)		UG (GaP)	Unit
Reverse Voltage	V <sub>R</sub>	5	V
Forward Current	I <sub>F</sub>	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i <sub>FS</sub>	140	mA
Power Dissipation	P <sub>T</sub>	105	mW
Operating Temperature	T <sub>A</sub>	-40 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds		

Operating Characteristics (TA=25°C)		UG (GaP)	Unit
Forward Voltage (Typ.) (I <sub>F</sub> =10mA)	V <sub>F</sub>	2.0	V
Forward Voltage (Max.) (I <sub>F</sub> =10mA)	V <sub>F</sub>	2.5	V
Reverse Current (V <sub>R</sub> =5V)	I <sub>R</sub>	10	uA
Wavelength of Peak Emission (I <sub>F</sub> =10mA)	λ P	565	nm
Wavelength of Dominant Emission (I <sub>F</sub> =10mA)	λ D	568	nm
Spectral Line Full Width At Half-Maximum (I <sub>F</sub> =10mA)	Δλ	30	nm
Capacitance (V <sub>F</sub> =0V, f=1MHz)	C	15	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (I <sub>F</sub> =10mA) mcd		Wavelength nm λ P	Viewing Angle 2 θ 1/2
				min.	typ.		
XLUG25C	Green	GaP	Green Transparent	8	29	565	100°
Published Date : MAY 22,2005				Drawing No :XDSA2368		V3 Checked : B.L.LIU P.1/3	



❖ UG



Remarks:

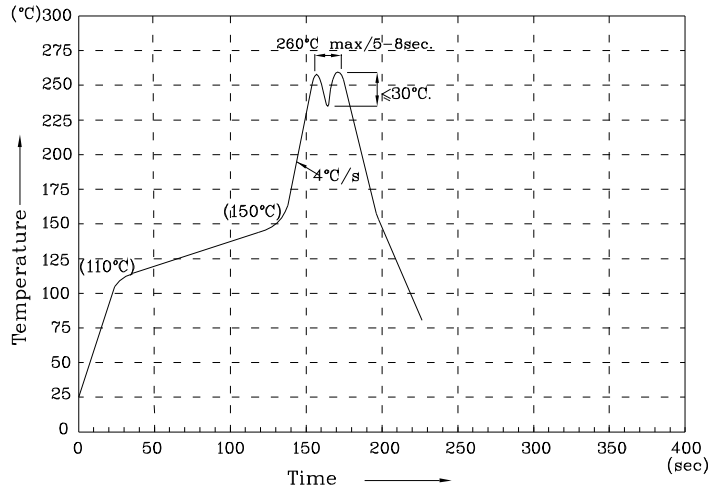
If special sorting is required (e.g. binning based on forward voltage, luminous intensity or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

XLUG25C

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85 degree°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. No more than once.